

1 2 3 4 5 6

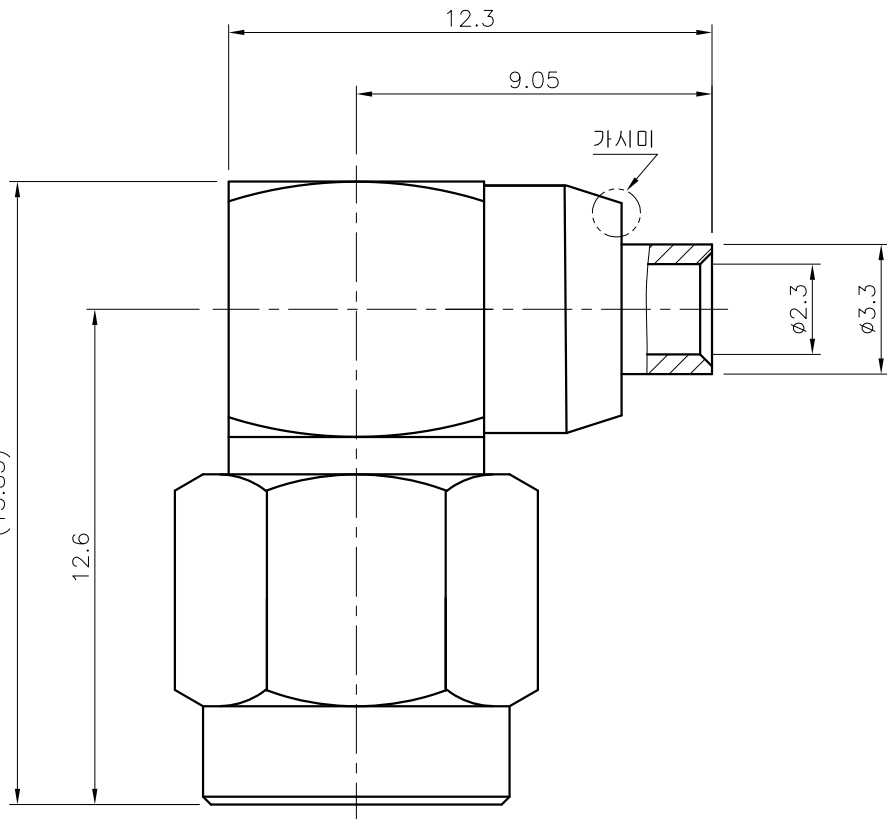
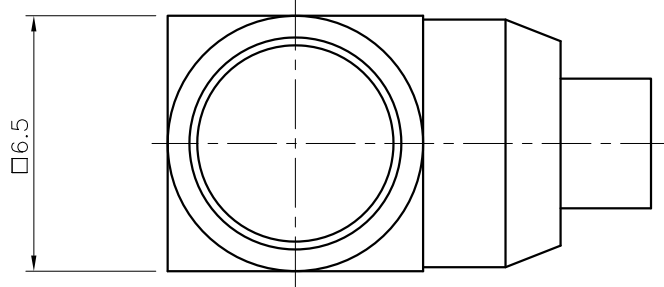
A

B

C

D

(15.85)



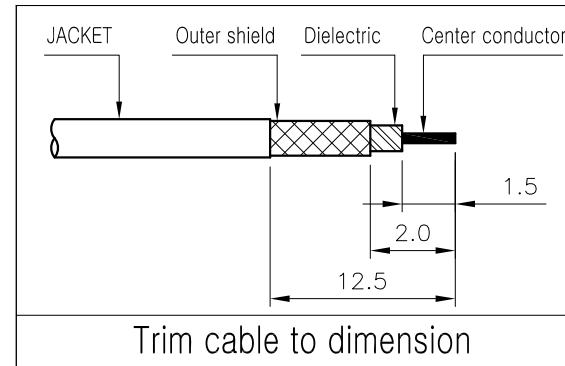
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2021.04.27.

A

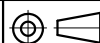
B

C

D



8	RING	1	SUS	부동태 처리	DSR00002-5/1
7	COVER	1	MBsBD	Nickel Plate	DCO00114-5/1
6	CAP	1	MBsBD	Nickel Plate	DCU00005-5/2
5	INSULATOR	1	TEFLON		DIN01015-N/1
4	GASKET	1	SILICONE RUB		DGK00004-N/1
3	CONTACT	1	MBsBD	Gold Plate	DCT00300-5/1
2	BODY (B)	1	MBsBD	Gold Plate	DBD03252-5/6
1	BODY (A)	1	ZnDC	Nickel Plate (3~4 μ m)	DBD02994-5/3
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2021. 04. 27.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle ±1°	APPROVED BY I.C.KIM					
MATERIAL _____		CHECKED BY		TITLE SMA50 CABLE PL 85			
		DRAWN BY S.Y.EUN					
FINISH _____		SCALE 5/1	UNIT mm		A4	DWG NO. CN02748-7/7	
						REVISION	I R

1 2 3 4 5 6